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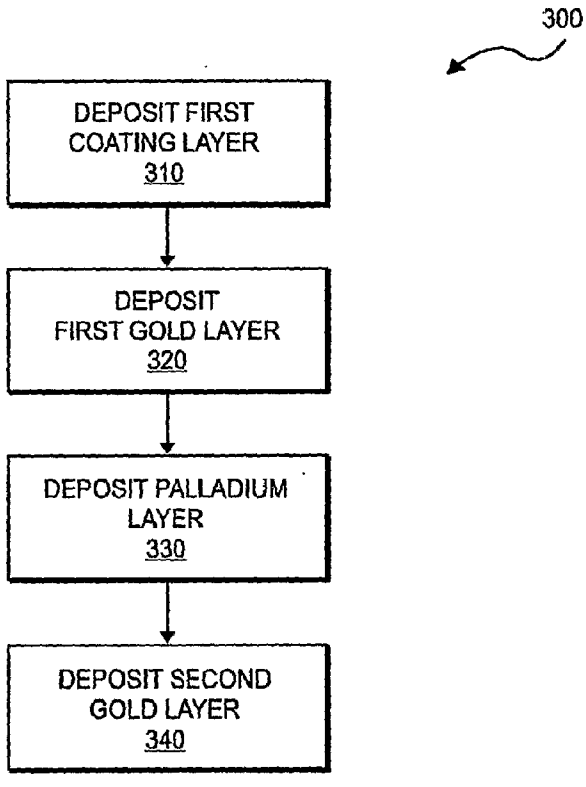
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(54) Title: LOW RESISTIVITY PACKAGE SUBSTRATE AND ITS MANUFACTURING METHOD



(57) Abstract: A method includes forming a coating on a land contact (210) of a package substrate, the coating including a first material (240) disposed between a first layer (230) and a second layer (250), each of the first layer and the second layer being made of a second material including gold. Am apparatus includes a package substrate including a plurality of land contacts wherein each of the plurality of land contacts includes a coating including a first material disposed between a first layer and a second layer, each of the first layer and the second layer being made of a second material including gold.

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